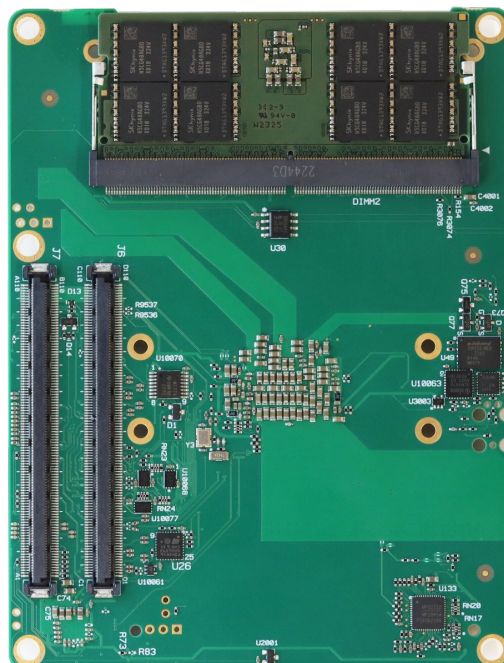
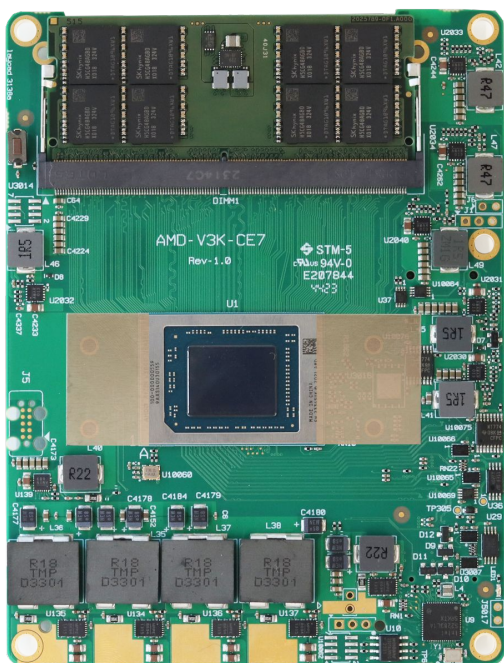


Ryzen V3000 CX7

COM Express Type 7 Based on AMD Embedded Ryzen V3000



Overview

AMD Ryzen™ Embedded V3000 COM7 brings the high-performance "Zen 3" CPU x86 core architecture to the V-Series portfolio, and deliver new levels of processing power, thermal efficiency and high-speed I/O connectivity in a compact, cost effective standard COM7. Providing seamlessly scalable module performance for a wide range of storage, networking and edge systems.

Fitting Embedded Landscape

The COM Express module offered for both Commercial and Industrial grade applications support temperature range from low -40°C up to high +85°C, outperforming low profile. Longevity commitment 10 years. AMD Ryzen™ Embedded V3000 are optimized for enterprise reliability in 24x7 operating environments with demanding workload requirements.

Connectivity

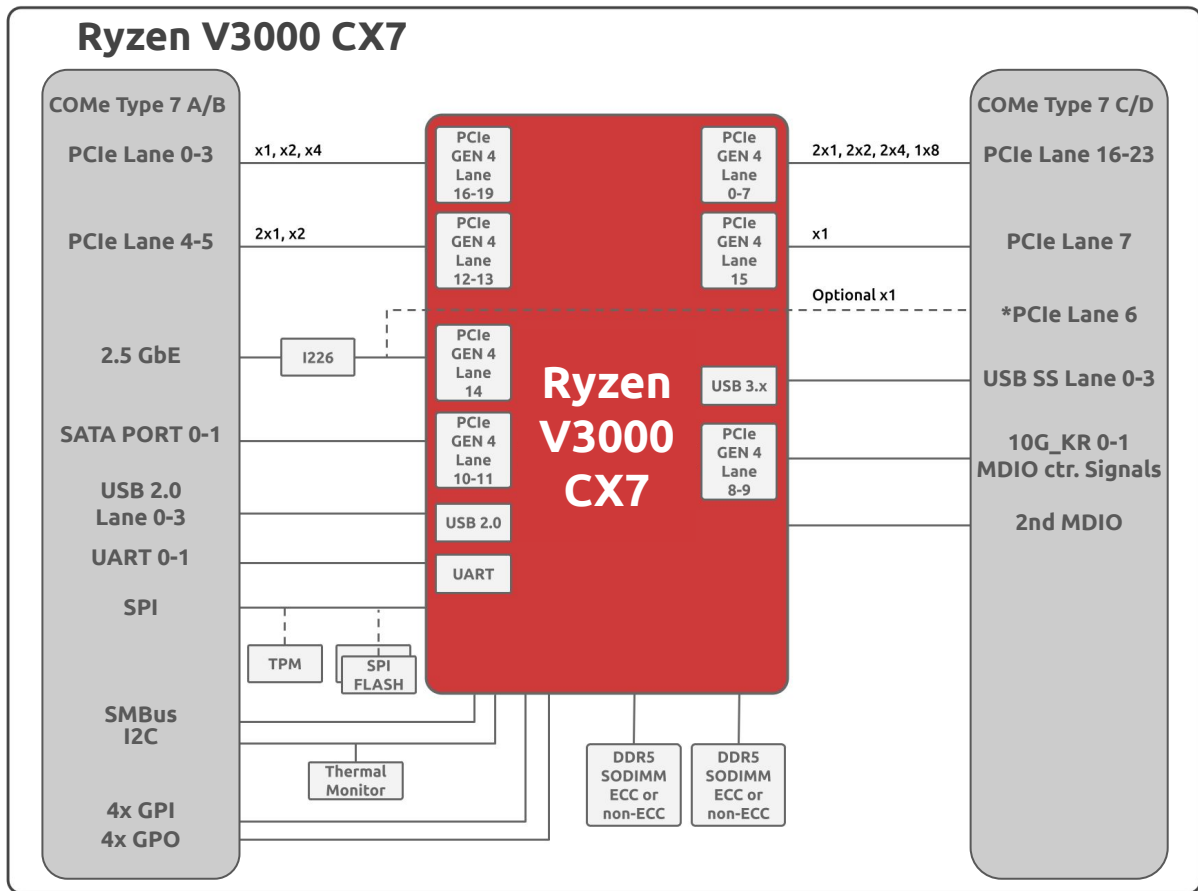
SolidRun AMD Ryzen V3000 COM7 is a COM Express Basic size Type 7 computer-on-module powered by the eight-core AMD Ryzen Embedded V3000 processor with twenty PCIe Gen 4 lanes, two 10GBASE-KR interfaces, on board 2.5GbE PHY and up to 96GB dual-channel DDR5 (ECC/non-ECC) SO-DIMM. The module PCB is ready to host special (Optional) accessories support rugged and extreme thermal environmental condition.

Target Applications

SolidRun AMD Ryzen V3000 COM7 targets wide range of embedded application such as server class applications engineered for tomorrow requirements: Unmanned Aerial vehicles, autonomous driving, 5G Applications, communication systems, Rugged servers, Medical and AI applications.



Ryzen V3000 CX7



		Ryzen V3000 CX7
CPU Details	CPU Name	AMD Ryzen V3C18I AMD Ryzen V3C48 (Optional R7000 7840HS and R8000 8845HS headless with iGPU for compute only)
	CPU Type	- 8 Cores / 16 Threads - TDP 15W (V3C18I) / 45W (V3C48)
	CPU Speed	V3C18I: 1.9GHz base / 3.8GHz boost V3C48: 3.3GHz base / 3.8GHz boost
RAM		Up to 96GB (2x 48GB) ECC/non-ECC DDR5 Up to 4800 MT/s (5600 MT/s for 7840HS and 8845HS) Via two SODIMM sockets
Networking	Ethernet	on-board 1x2.5Gbe 2x 10GBASE-KR
Security Watchdog	TPM	Infineon TPM 2.0 (Optional, SPI based) Dedicated MCU
Connectivity	USB 2.0	4x USB 2
	USB 3.0	4x USB 3.2
	PCIe	x20 (Gen4)
	I2C	x1 x1 eSPI
	SPI	x2
	UART	x2
	GPIO	x4 GPI / x4 GPO / x4 SDP
Physical	SATA	2x SATA Gen3 6 Gbps (V3C18I and V3C48 only)
	BIOS SPI flashing	Via 10 pin tag-connect interface
	Form factor	125mm x 95 mm
Power	Mating height	2x220 Pin COM headers 5mm / 8mm
	Profile	Total height (5mm mating height) 11.2mm
Environment	Temperature	Commercial grade (CPU V3C48): 0°C to 85°C Industrial grade (CPU V3C18I): -40° to 85°C
	Vibration	SO-DIMM fastening fixture